

**INDEX BY DEVICE TYPE OF REGISTERED  
MICROELECTRONIC STANDARD OUTLINES (MS)**

<b>FAMILY</b>	<b>REGISTRATION NO.</b>
<b>BALL GRID ARRAY</b>	
Rectangular Plastic BGA, 1.27 mm, 1.0 mm Pitch	MS-028
Plastic Square BGA 1.0mm, 1.27mm 1.50 mm Pitch	MS-034
<b>CHIP CARRIERS (LCC &amp; PLCC)</b>	
LEADLESS Type A .050" Centers	MS-002
LEADLESS Type B .050" Centers	MS-003
LEADLESS Type C .050" Centers	MS-004
LEADLESS Type D .050" Centers	MS-005
LEADED Type A .050" Centers	MS-006
LEADED Type A .050" Centers	MS-007
LEADED Type B .050" Centers	MS-008
LEADLESS Chip Carrier .040" Centers	MS-009
LEADLESS Single Layer .040" Centers	MS-014
Plastic Chip Carrier .050" Spacing	MS-016
Plastic Chip Carrier .050" Spacing	MS-018
<b>DUAL-IN-LINE FAMILY (DIP)</b>	
.300" Row Spacing	MS-001
.400" Row Spacing	MS-011
.400" Row Spacing Plastic	MS-010
.300/.400/.600/.900 SIDE BRAZED	MS-015
.300 (.070" pitch)	MS-019
.600 (.070" pitch)	MS-020
.750 (.070" pitch)	MS-021
.300" Row Spacing Ceramic	MS-030
.400" Row Spacing Ceramic	MS-031
.600" Row Spacing Ceramic	MS-032
<b>PIN GRID ARRAY (PGA)</b>	
Ceramic PGA .100" Pitch Cavity Down	MS-017
<b>QUAD FLATPACK (QFP)</b>	
Plastic 1.0 & 1.4 mm thick, 2mm footprint	MS-026
Metric Plastic 1.0, 0.8, 0.65 mm pitch	MS-022

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<b>FAMILY</b>	<b>REGISTRATION NO.</b>
<b>QUAD FLATPACK (QFP) (cont'd)</b>	
Fine Pitch Plastic QFP 2.6 mm footprint	MS-029
<b>SMALL OUTLINE (SO &amp; TSOP)</b>	
.150" Body Width SO	MS-012
.300" Body Width SO	MS-013
.300" Plastic SOJ	MS-023
.400" SOJ	MS-027
10.16 mm Body TSOPII	MS-024
7.62 mm Body TSOPII	MS-025